



09/ 813164

Docket No.: M4065.0187/P187-B  
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Letters Patent of:  
Scott E. Moore

Patent No.: 6,830,666 B2

Issued: December 14, 2004

For: ELECTROPLATING APPARATUS AND  
METHOD

Certificate  
AUG 17 2005  
of Correction

REQUEST FOR CERTIFICATE OF CORRECTION  
PURSUANT TO 37 CFR 1.322

Commissioner for Patents  
MS: Post Issue  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Upon reviewing the above-identified patent, Patentee noted a typographical error which should be corrected.

In the Detailed Description of Preferred Embodiments:

Col. 3, line 48 reads "of the wafer 18, die" should read --of the wafer 18, the--

The error described above was not in the application as-filed or amended by the Patentee. The error now sought to be corrected is an inadvertent typographical error by the USPTO, the correction of which does not involve new matter or require reexamination.

Transmitted herewith is a proposed Certificate of Correction effecting such amendment. Patentee respectfully solicits the granting of the requested Certificate of Correction.

Since the error occurred on the part of the U.S. Patent and Trademark Office, no fee is believed to be due. The Commissioner, however, is also hereby authorized to charge any deficiency in the fees filed, asserted to be filed or which should have been filed herewith (or with any paper hereafter filed in this application by this firm) to our Deposit Account No. 04-1073, under Order No. M4065.0187/P187-B. A duplicate copy of this paper is enclosed.

Dated: August 16, 2005

Respectfully submitted,

By 

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**UNITED STATES PATENT AND TRADEMARK OFFICE  
CERTIFICATE OF CORRECTION**

PATENT NO. : 6,830,666 B2  
DATED : December 14, 2004  
INVENTOR : Scott E. Moore

It is certified that an error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In the Detailed Description of Preferred Embodiments:

Col. 3, line 48 reads "of the wafer 18, die" should read --of the wafer 18, the--

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No. of additional copies 0

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